UNCONTROLLED DOCUMENT

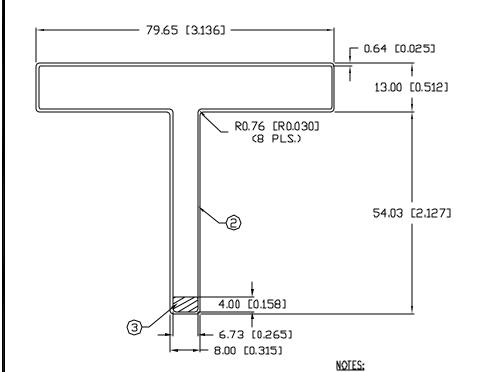
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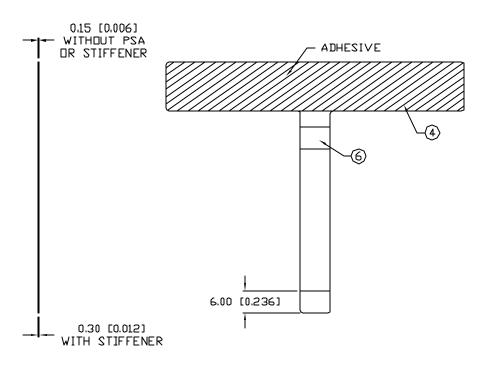
PART NUMBER

IXP-H12864-FMI

PRELIMINARY IN P/N DIR

REV.





1. MATERIAL: 10Z COPPER (1.4MIL) ON 2MIL POLYIMIDE AND A 1.8MIL PIC 1025 COVERLAY. PLATING: BRIGHT TIN.

ADHESIVE: 3M Y946D VHB PSA (2MIL)

- Z. NON-EXPOSED COPPER IS INDICATED AS SHOWN, COPPER TO BE POSITIONED TO WITHIN 0.64 OF ALL PART EDGES.
- 3. EXPOSED COPPER TO BE LOCATED IN THE CONTACT AREA ONLY. POSITION IS INDICATED AS SHOWN. PLATING TO BE BRIGHT TIN.
- 4. ADHESIVE TO BE APPLIED AS SHOWN, ADHESIVE TO BE FLUSH WITH EDGES OF PART.
- 5. PART MATES WITH A 7 POSITION MOLEX 52610-0790 ZIF STYLE CONNECTOR.
- 6. PART MAY CONTAIN A STIFFNER IN THIS AREA DUE TO CURRENT PANELIZATION. THIS STIFFNER IS NOT A REQUIREMENT.

*UNCONTROLLED DOC* \*UNIESS OTHERWISE SPECFED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 (±0.039), XX=±0.5 (±0.020), XXX=±0.25 (±0.010), XXXX=±0.127 (±0.005). LEAD SIZE=±0.05 (±0.002), LEAD LENGTH=±0.75 (±0.030). NN=+DECIMAL PRECISION WAX.=+0.00 (±0.030). NN=+

PART NUMBER LXP-H12864-EMI

REV.

EMI FLEXCABLE FOR LCM-H12864GWF/C.

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RELIABILITY NOTE OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.



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DRAWN BY:

CHECKED BY: APPROVED BY:

DATE: 8.6.03 PAGE: 1 OF 1 SCALE:

N/A

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